

REMARKS

In the pending Office Action, the drawings were requested to be corrected.

Further, claims 87-91, 95, 98-102, 106-110 and 112-114 were rejected under §102(b) as being anticipated by Kanji (U.S. Patent 5,067,007), and claims 96-97, 103-105 and 111 were rejected under §103(a) as being unpatentable over Kanji.

In this amendment, Applicant has submitted proposed drawings corrections and has amended claims 87 and 106. Accordingly, all claims considered in the Office Action are currently pending.

With respect to the drawings objection, the Applicant believes that this objection is improper and that there would be no confusion with respect to the drawings as originally submitted. The specification describes the various materials and properties of these structures and those in the art would be aware of the materials and properties without reference to the cross-hatching or the Patent Office's rules in connection with cross-hatching. Thus, Applicant respectfully requests the Examiner to remove this objection. Alternatively, Applicant has proposed an amendment to the drawings in which all of the cross-hatching is removed. Applicant submits that these proposed drawings are acceptable and should, in the alternative, if the Examiner does not remove the objection to the drawings, be approved by the Examiner.

Applicant will now address the rejection of the claims based upon the prior art Kanji reference.

Kanji describes a device for mounting an integrated circuit onto a surface of a printed circuit board. As is well known in the art, such a device is fixedly secured to the circuit board such that the device will not move when the circuit board is jarred, etc. Kanji makes it clear that both ends of the lead pins 11 are fixedly secured at both ends of these pins. For example, Kanji states at column 5, lines 63-68 that "Upper ends of the lead pins 11 are joined to the electrodes 8 on the lower surface of the insulating substrate 4 via a brazing member 12 such as a silver(Ag)/copper(Cu) alloy or an adhesive such as the

solder, and lower ends of the lead pins 11 are joined to the electrodes 3 of the printed wiring board 1 via solder 13.” Clearly, Kanji is not describing a freestanding elongate element. Kanji’s lead pins are electrical interconnections but they are not freestanding resilient elongate elements which serve as electrical connections. Even if it is assumed that the upper end of the lead pin 11 is a “contact tip structure,” the upper end of the lead pin 11 is joined to an electrode 8 in a fixed manner which is not releasable or non-releasable. Thus, the upper end of the lead pin 11 is not a contact tip structure which is secured only to an end of a freestanding resilient elongate element. Further, it is clear that Kanji does not disclose or make obvious the amended limitations of claims 87 and 106. These limitations make it clear that the contact tip structure is non-releasably secured only to the end of the freestanding resilient elongate element when the freestanding resilient elongate element is conducting current as an electrical interconnection. Even again, for the sake of argument, if it is assumed that the upper end of the lead pin 11 is a contact tip structure, it is clearly not releasably secured to both the pin 11 as well as the bottom portion of the substrate 4. That is, the contact tip structure of Kanji is secured to more than a freestanding resilient elongate element.

Therefore, Applicants respectfully submit that claims 87 and 106 are not anticipated by Kanji. For at least the foregoing reasons, the claims which depend upon these two independent claims are also not anticipated by Kanji. In view of the foregoing discussion, Applicants submit that the § 102(b) rejections should be withdrawn.

The rejection of the pending claims 96-97, 103-105 and 111 under §103(a) should also be withdrawn as these claims incorporate the features of claims 87 and 106. As stated above, Kanji does not disclose, teach or suggest a contact tip structure as claimed by Applicants. Because Kanji fails to disclose, teach or suggest this structure, Applicants submit that the claimed invention would not have been obvious to a person of ordinary skill in the art in view of Kanji at the time of the claimed invention. In view of the foregoing

discussion, Applicants submit that the §103(a) rejections are overcome and thus Applicants respectfully request that the §103(a) rejections be withdrawn.

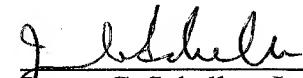
Applicants hereby petition for an extension of time to respond to the pending Office Action, and a check for the extension fee is enclosed.

Please charge any insufficiency or credit any overpayment to Deposit Account No. 02-2666.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN

Date: 9/10, 2001


James C. Scheller, Jr.
Reg. No. 31,195

12400 Wilshire Boulevard
Seventh Floor
Los Angeles, California 90025-1026
(408) 720-8300

FIRST CLASS CERTIFICATE OF MAILING (37 C.F.R. § 1.8(a))

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231 on: September 10, 2001.

Date of Deposit

Connie Thayer

Name of Person Mailing Correspondence

Connie Thayer

Signature

9-10-01

Date

VERSION WITH MARKINGS TO SHOW CHANGES MADE

Please amend claims 87 and 106 as indicated below.

87. (Three Times Amended) An electrical interconnection component comprising:
a freestanding resilient elongate element; and
a contact tip structure created in a first substrate and then secured only to an end of the freestanding resilient elongate element and released from said first substrate wherein the contact tip structure is non-releasably secured only to said end of the freestanding resilient elongate element when the freestanding resilient elongate element is conducting current as an electrical interconnection.

106. (Twice Amended) An electronics assembly comprising:
a substrate;
a freestanding resilient elongate element having a first end secured to the substrate; and
a contact tip structure created in another substrate and then secured only to a second end of the freestanding resilient elongate element opposing the first end and released from said another substrate wherein the contact tip structure is non-releasably secured only to the second end of the freestanding resilient elongate element when the freestanding resilient elongate element is conducting current as an electrical interconnection.

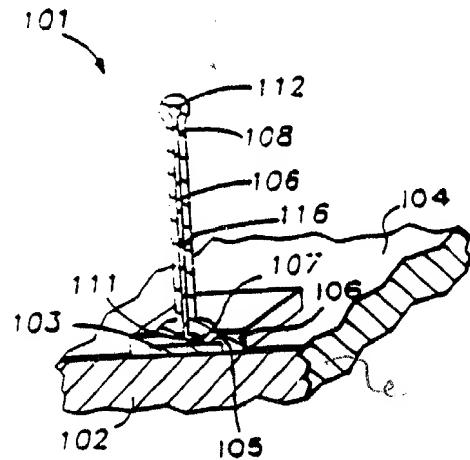


FIG. - 1

delete
all cross
hatching

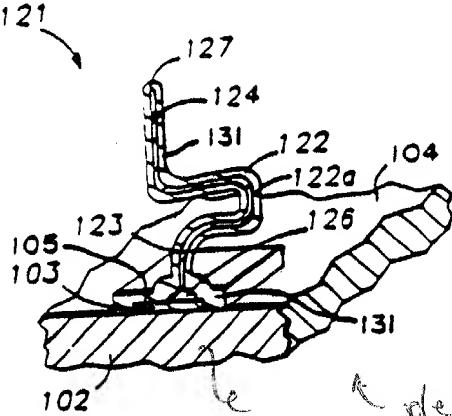


FIG. - 2

delete all
cross
hatching

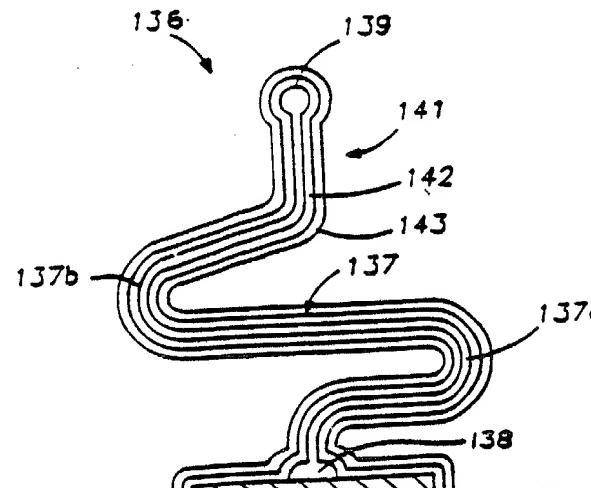


FIG. - 3

delete all
cross hatching

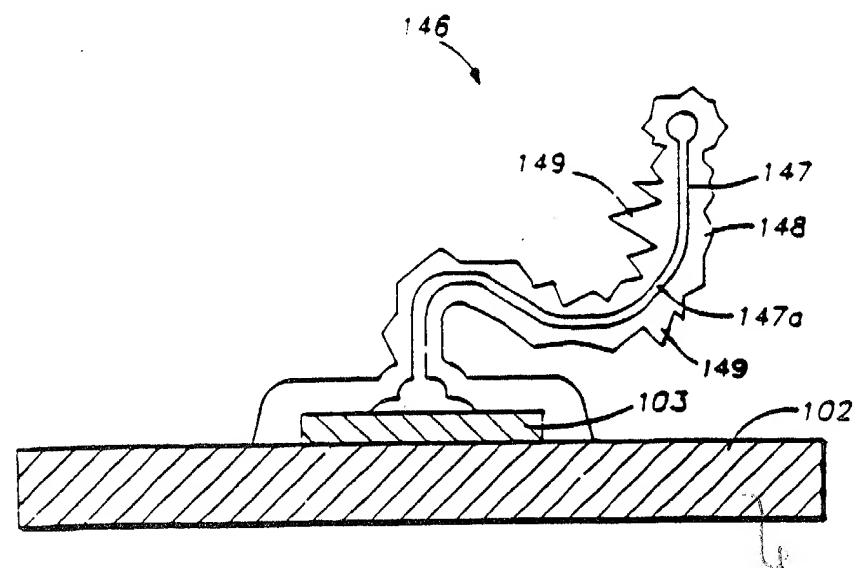


FIG. -4

delete all cross
hatching

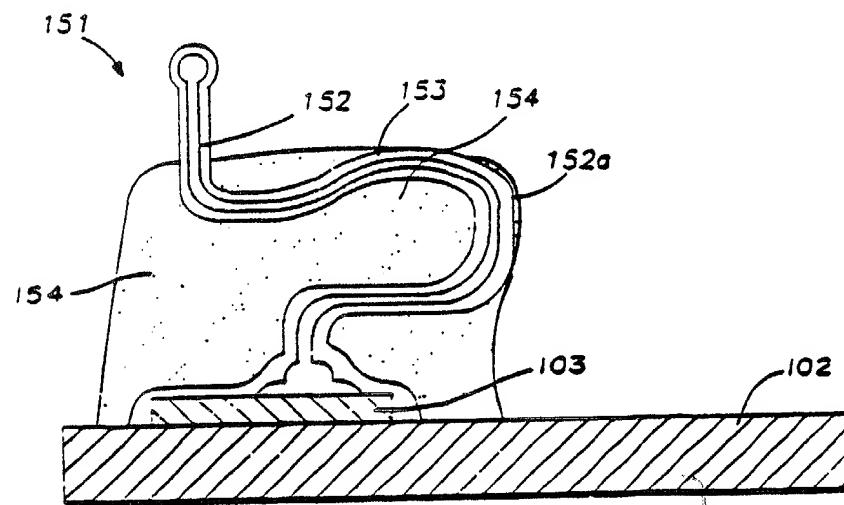
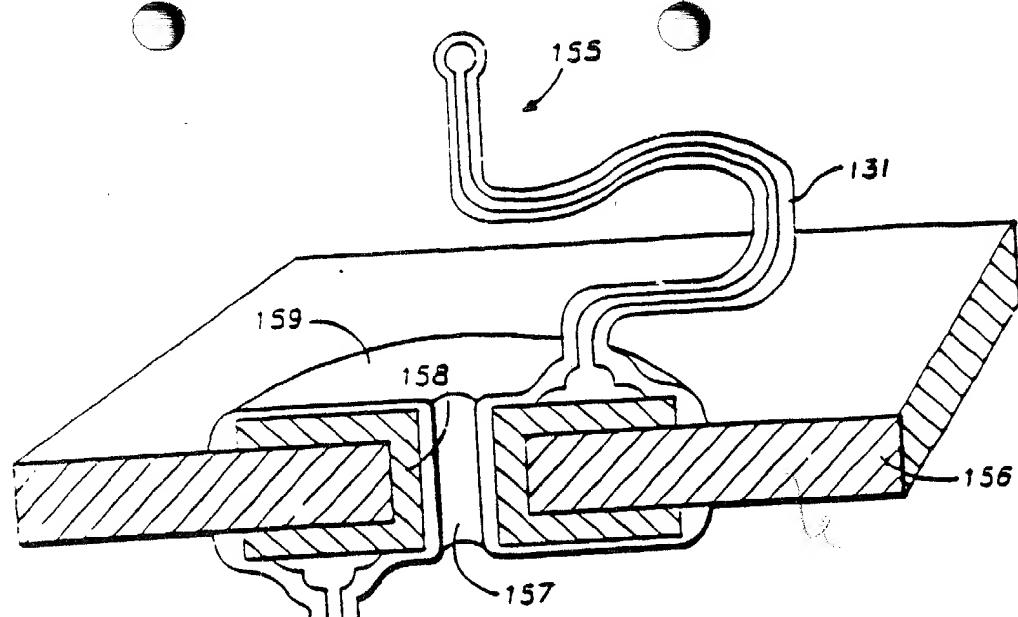


FIG. -5

delete all cross
hatching



L denote all excess
hatching

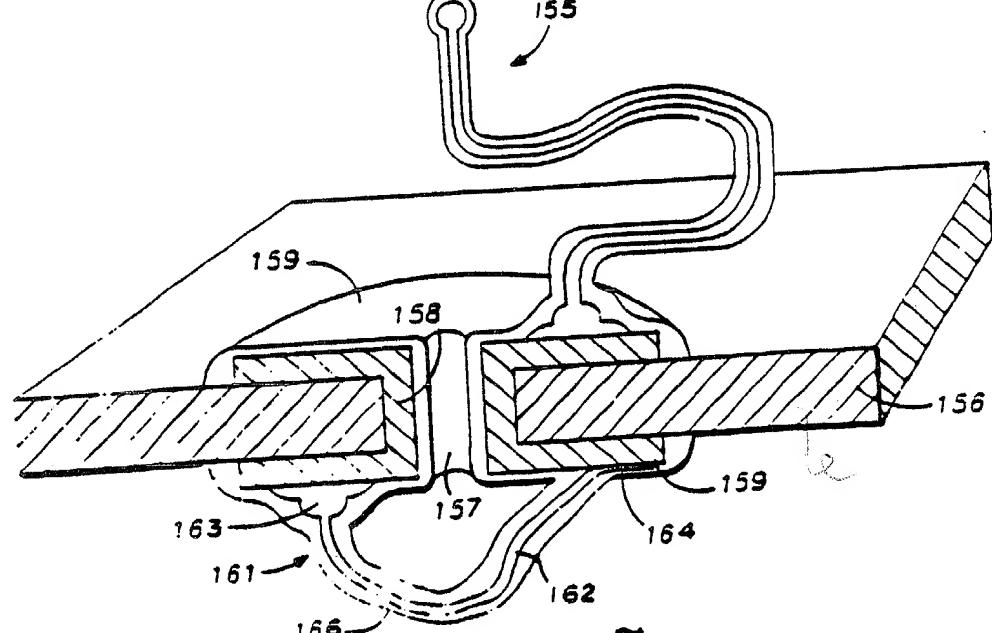
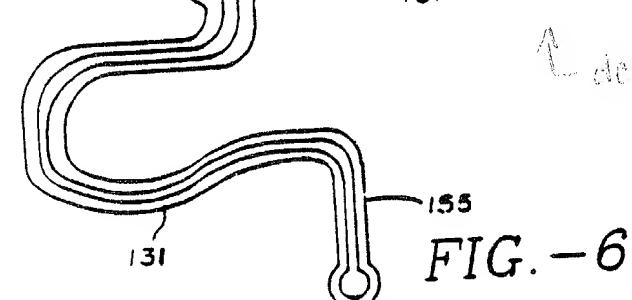


FIG. - 7

ditto as in previous drawing

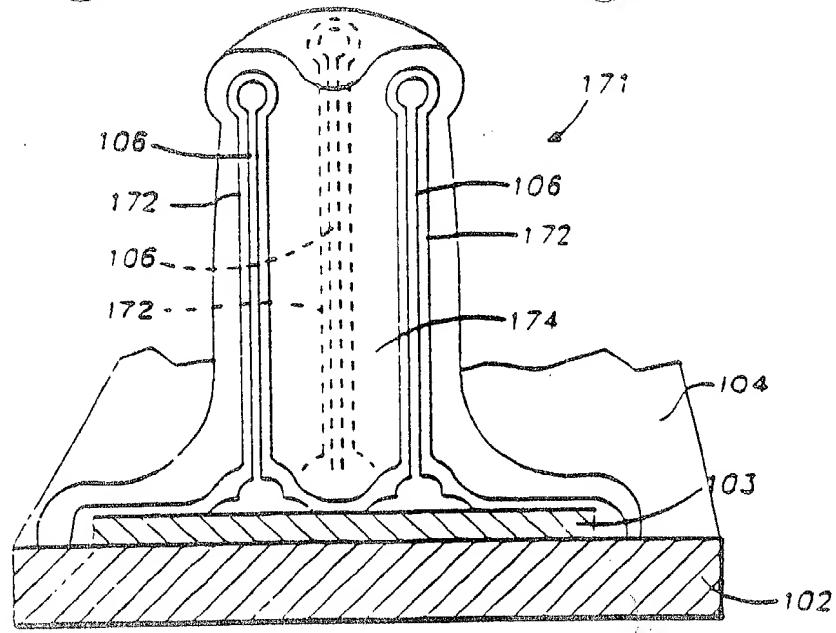


FIG. - 8

Plasma etching chamber

176

Exhaust port

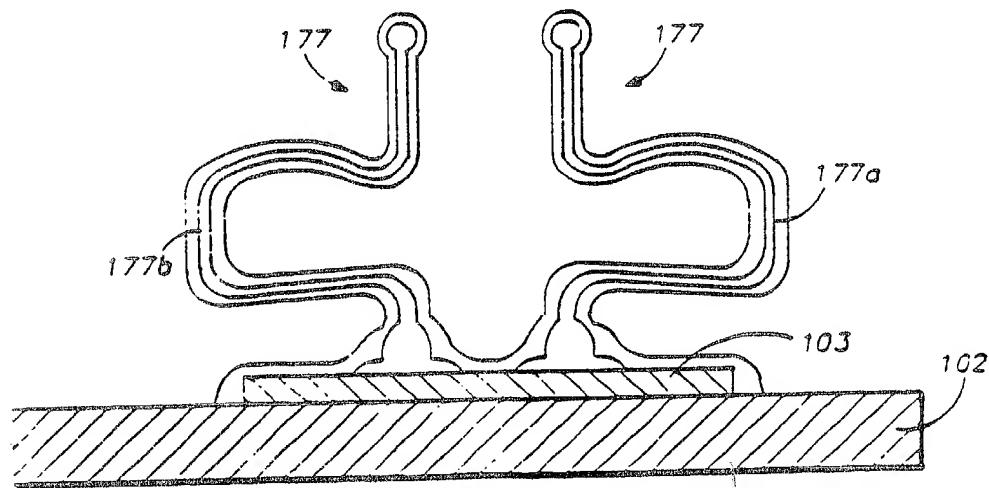


FIG. - 9

Plasma etching chamber

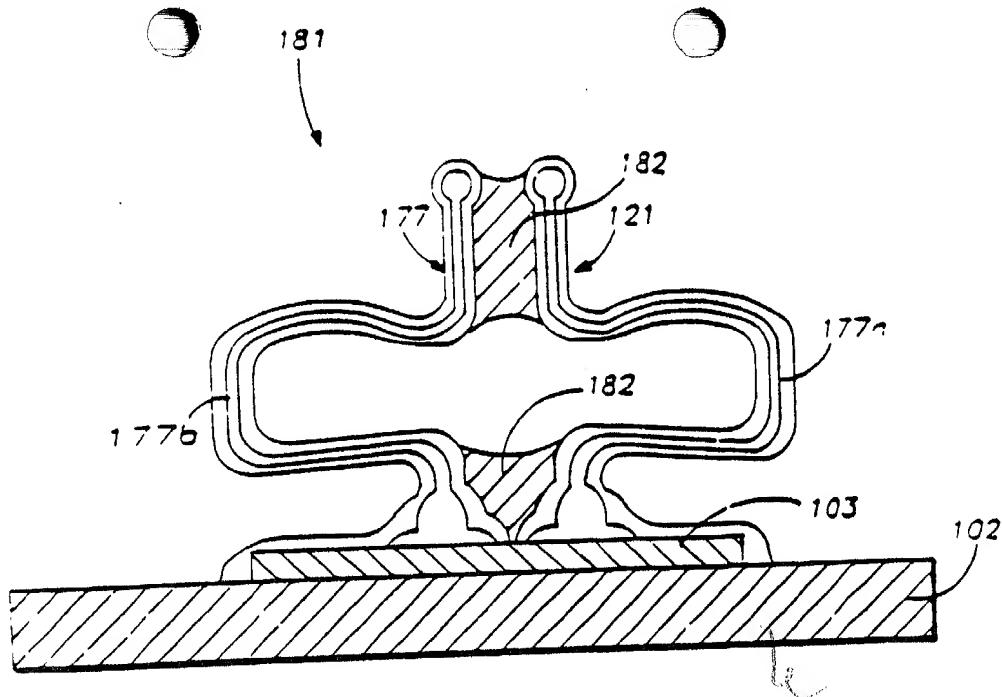


FIG. - 10

↑ delete all cross
hatching

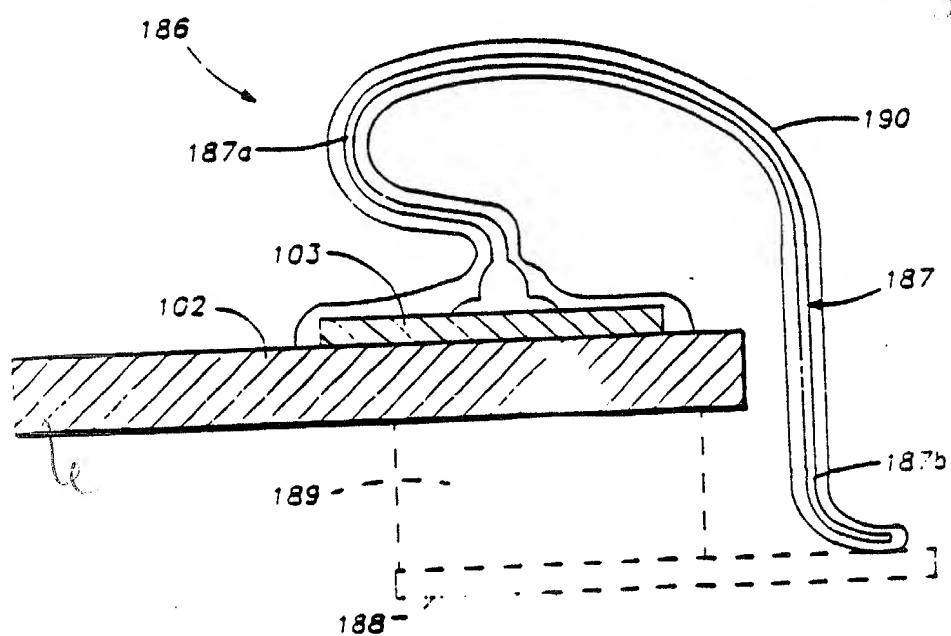


FIG. - 11

↑ delete all cross hatching

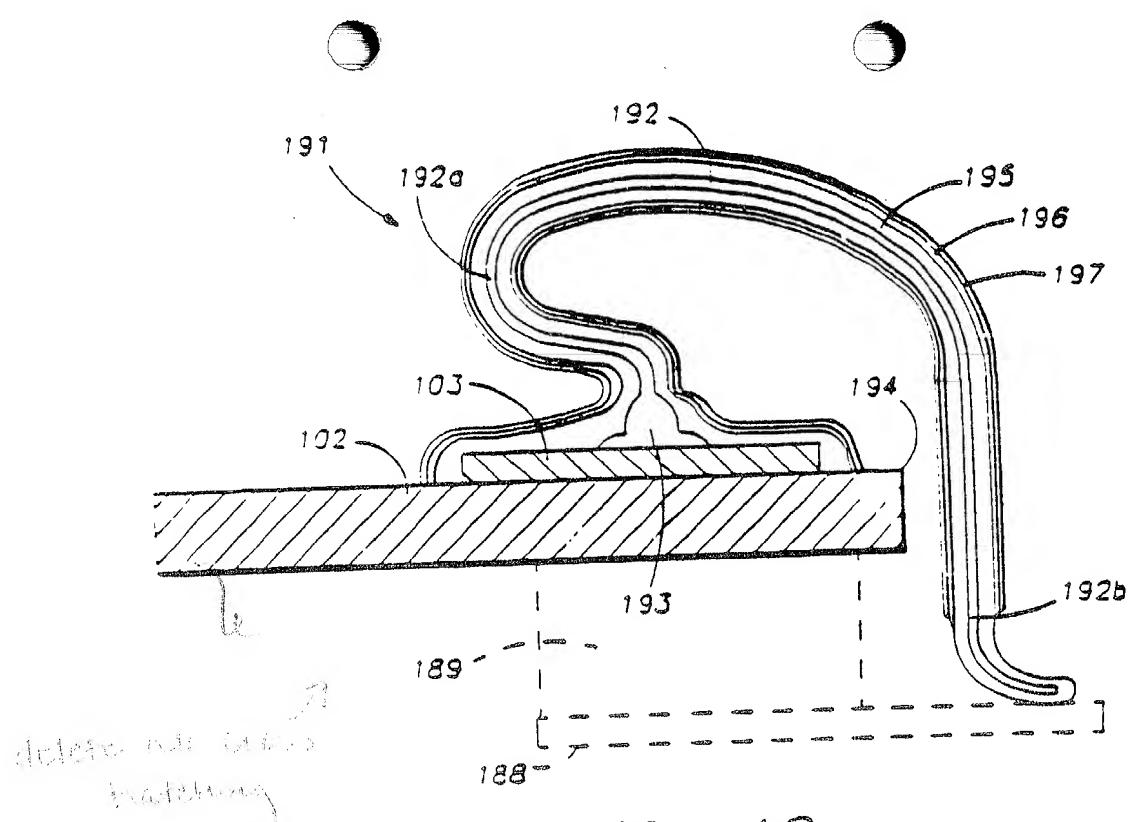


FIG. - 12

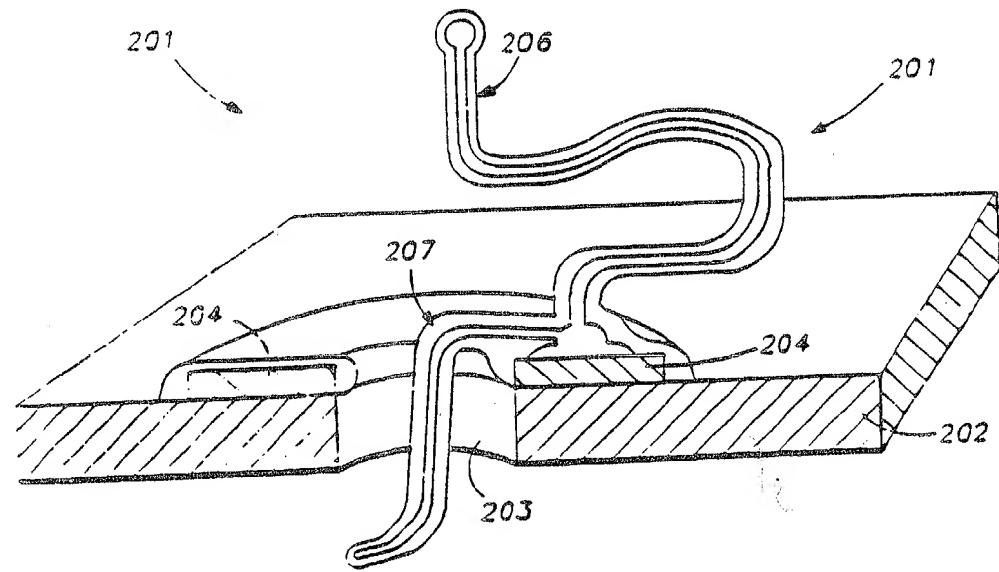
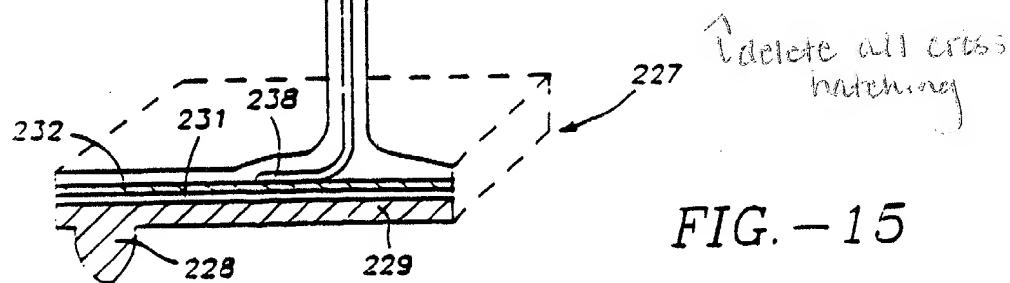
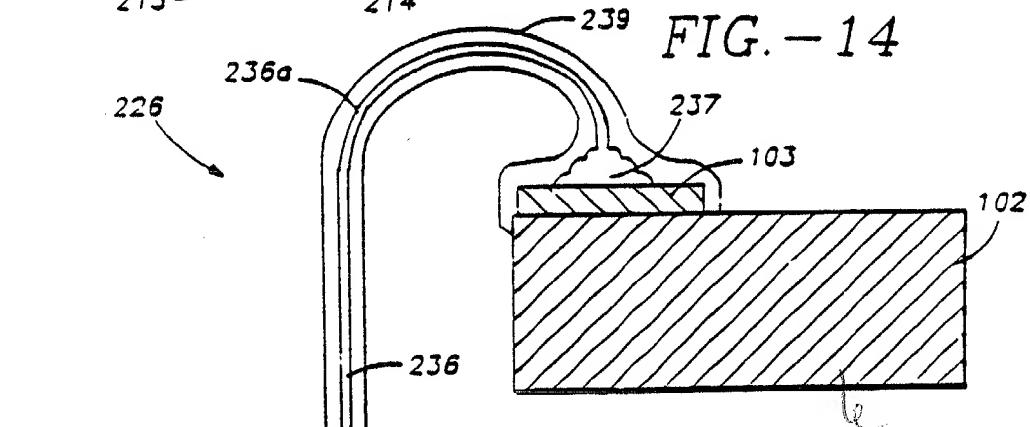
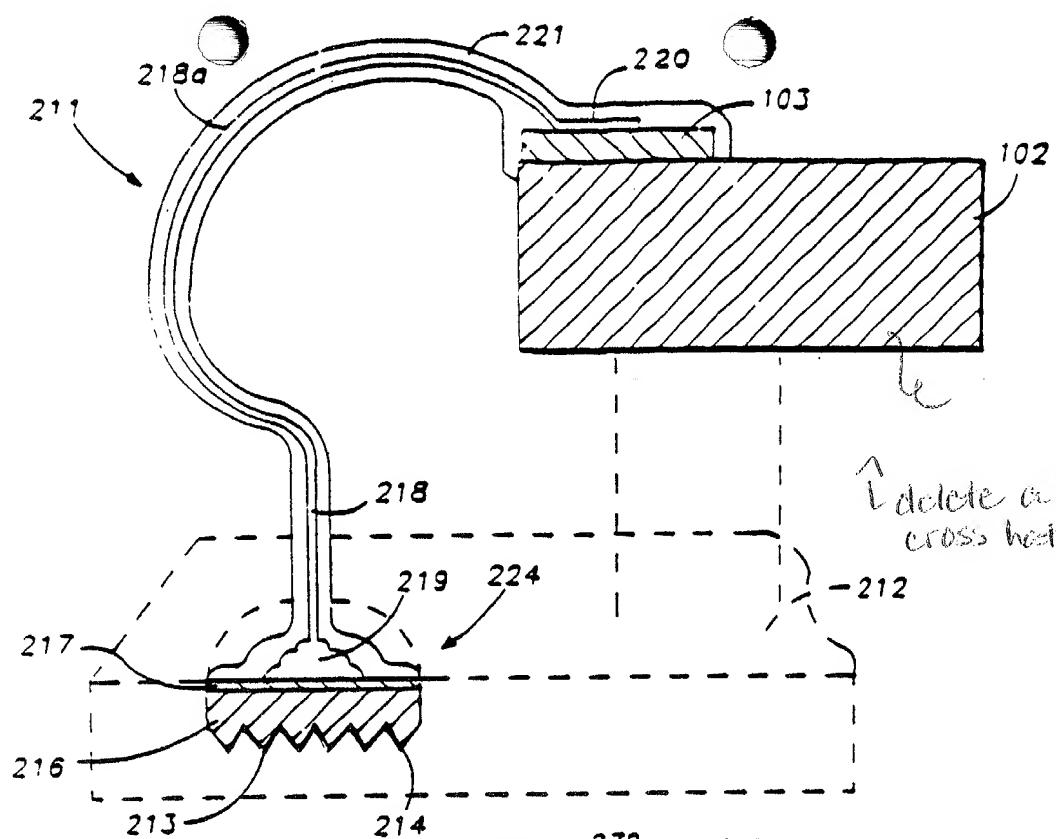


FIG. - 13



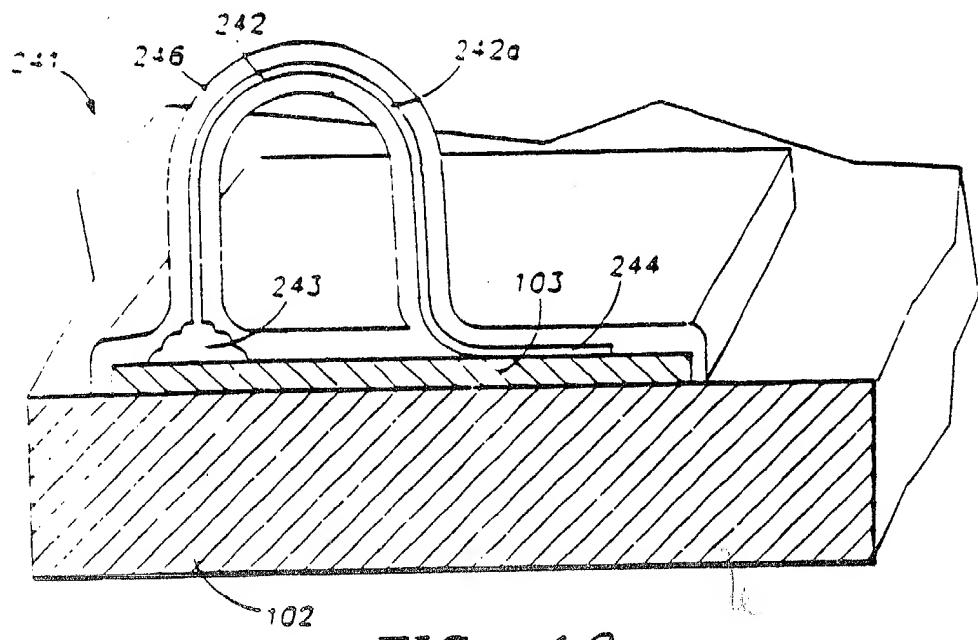


FIG. - 16

Capacitor cell circuit
(interior)

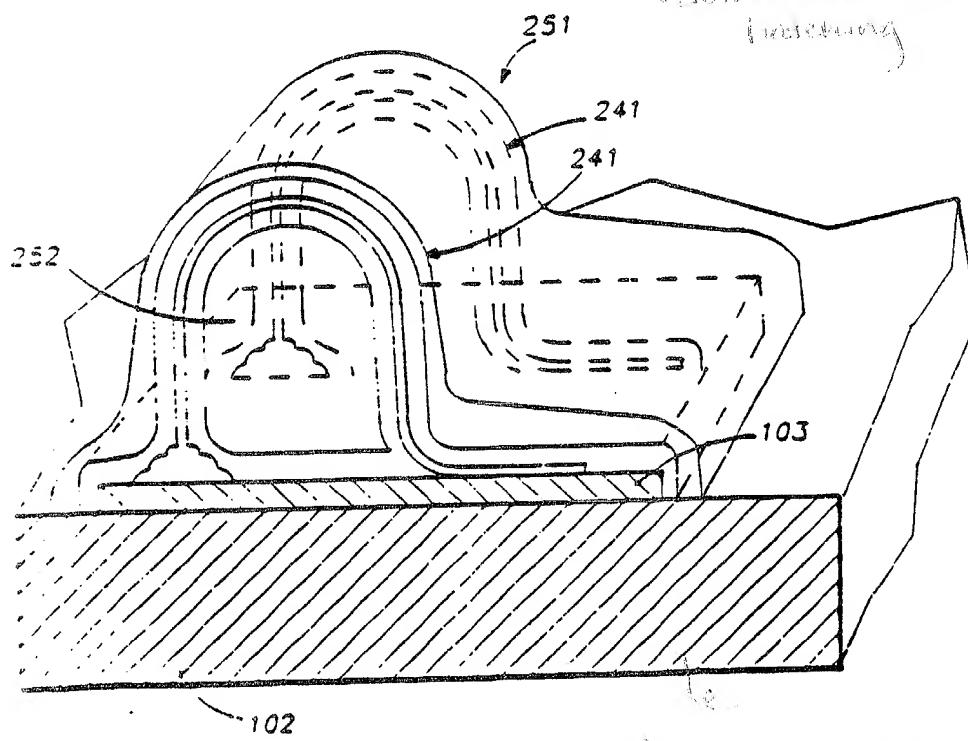


FIG. - 17

Inductor cell circuit
(interior)

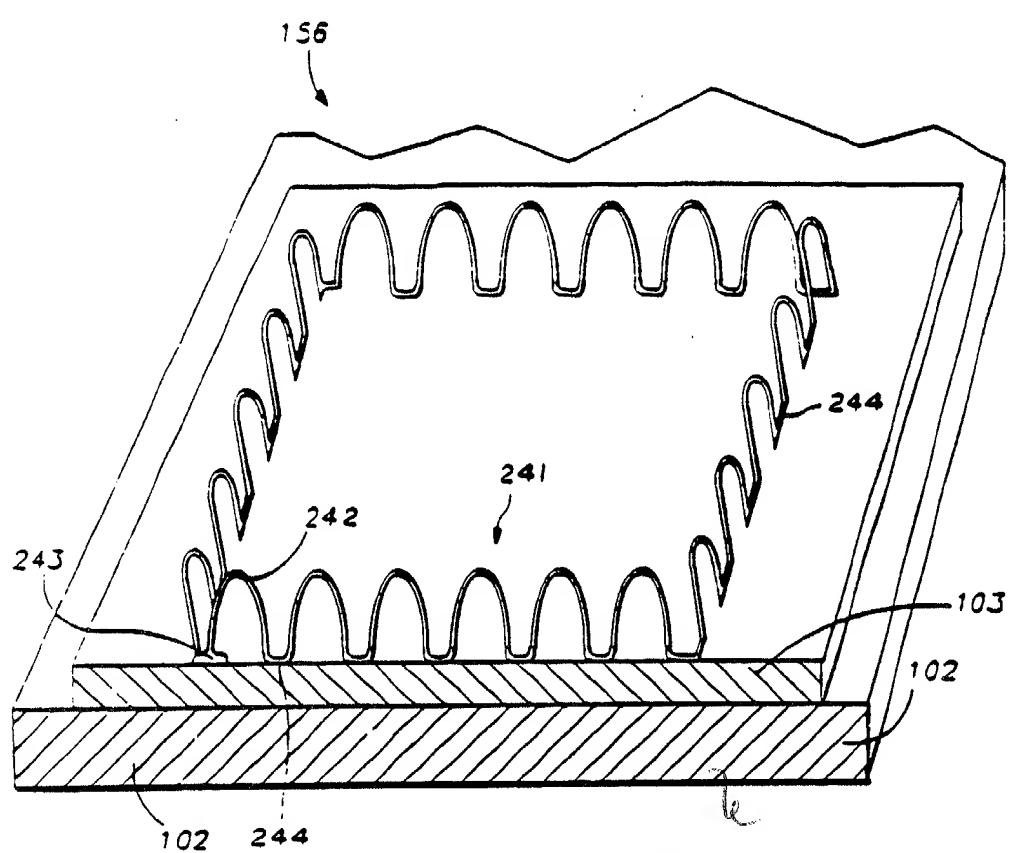


FIG. - 18 *↑ delete all cross hatching*

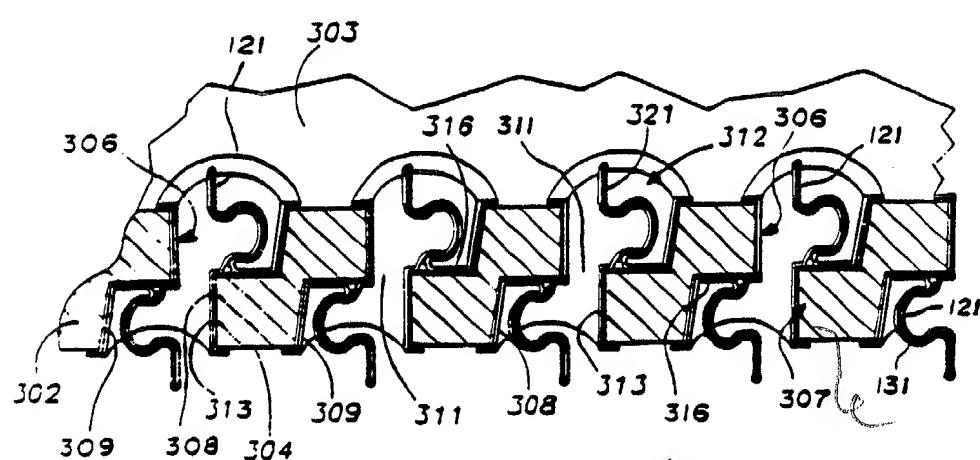
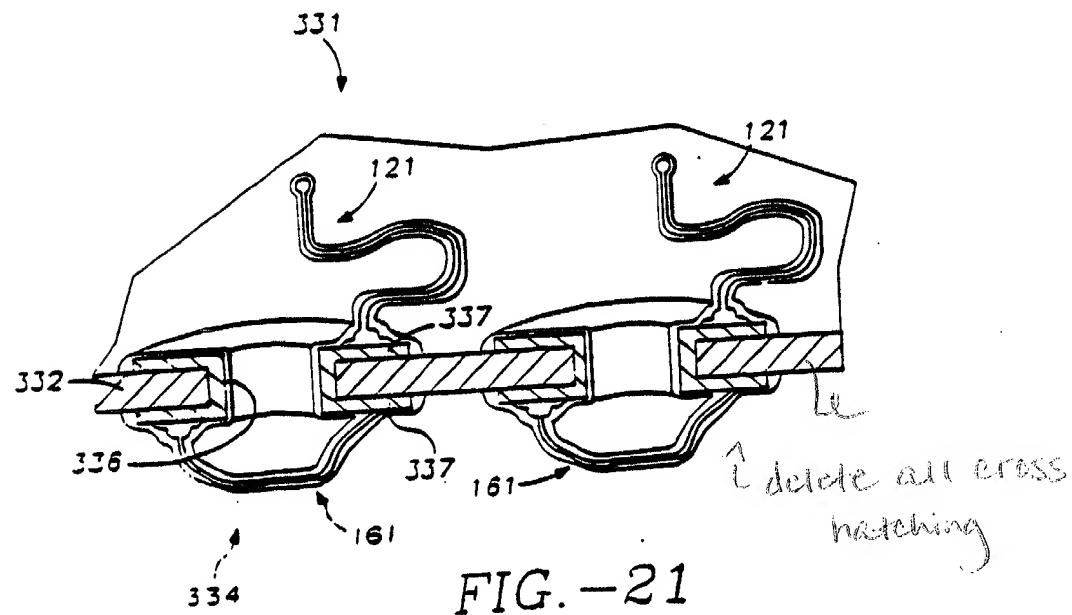
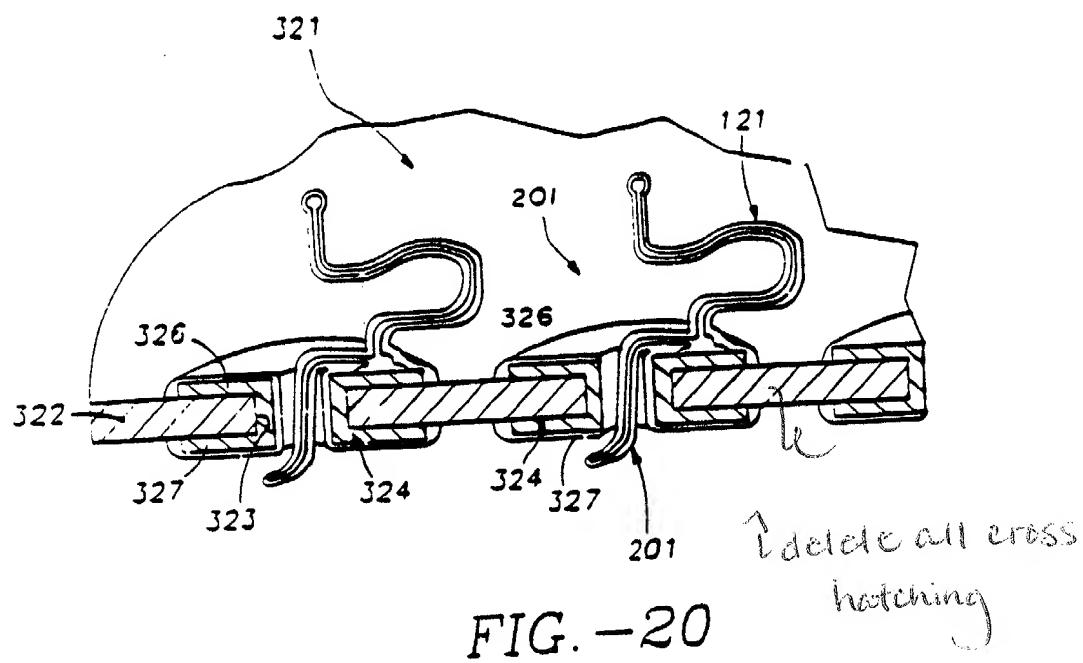


FIG. - 19 *↑ delete all cross hatching*



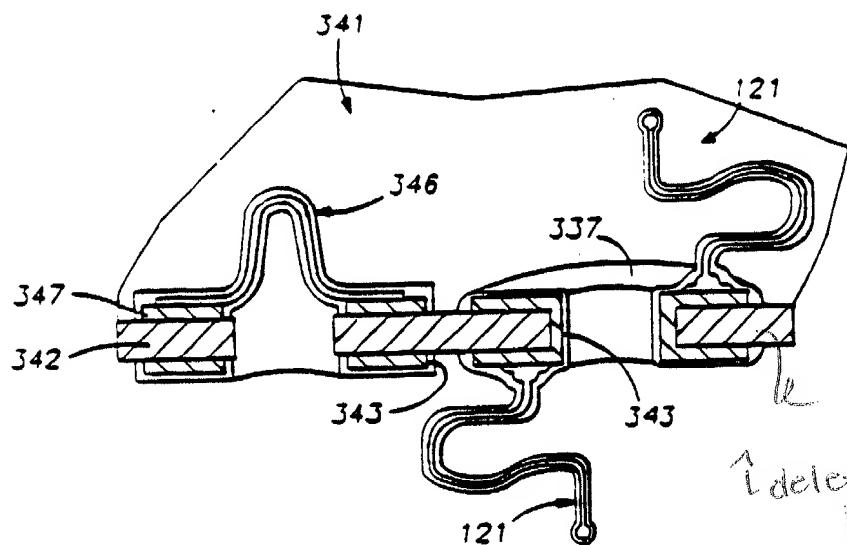


FIG. - 22

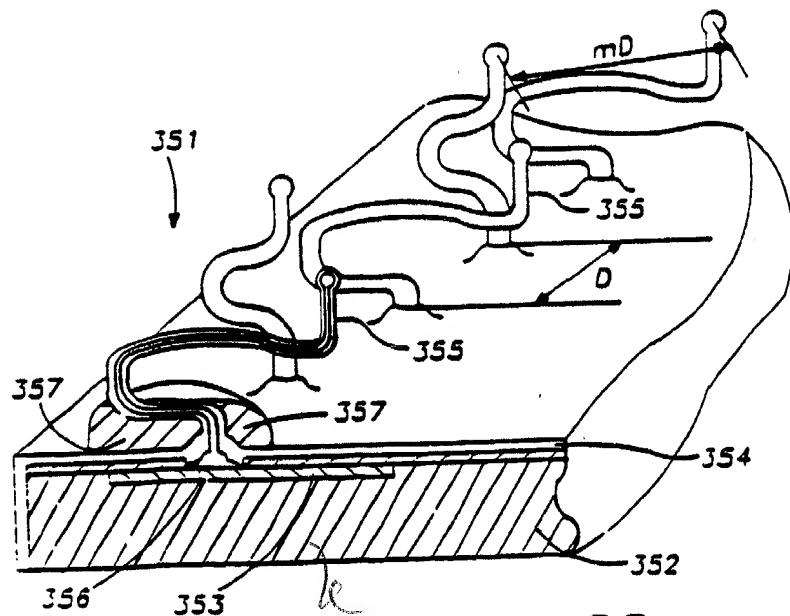


FIG. - 23

↑ delete all cross hatching

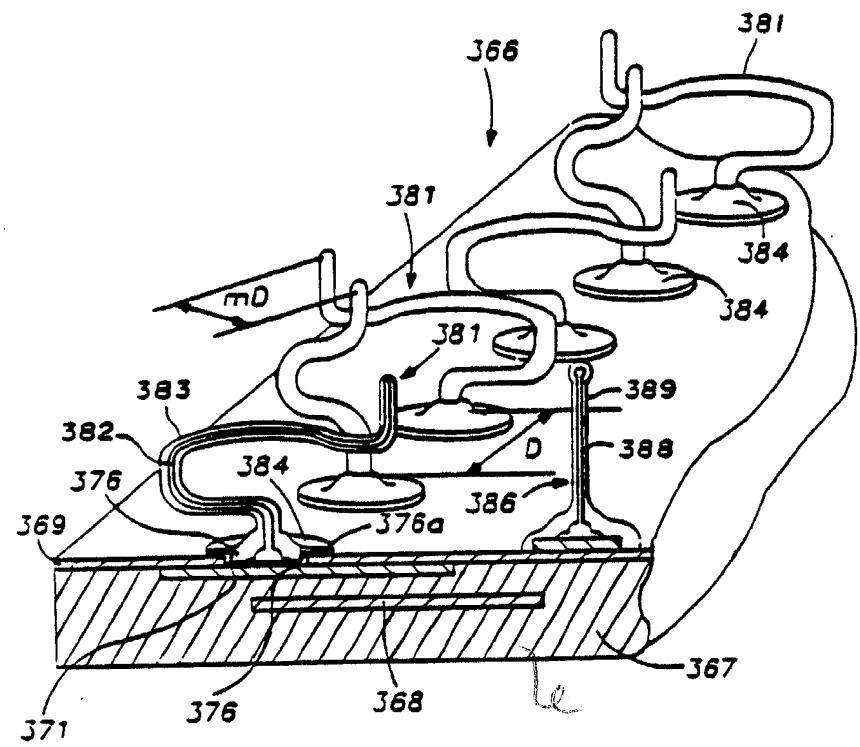


FIG. - 24

↑ Delete all cross hatching

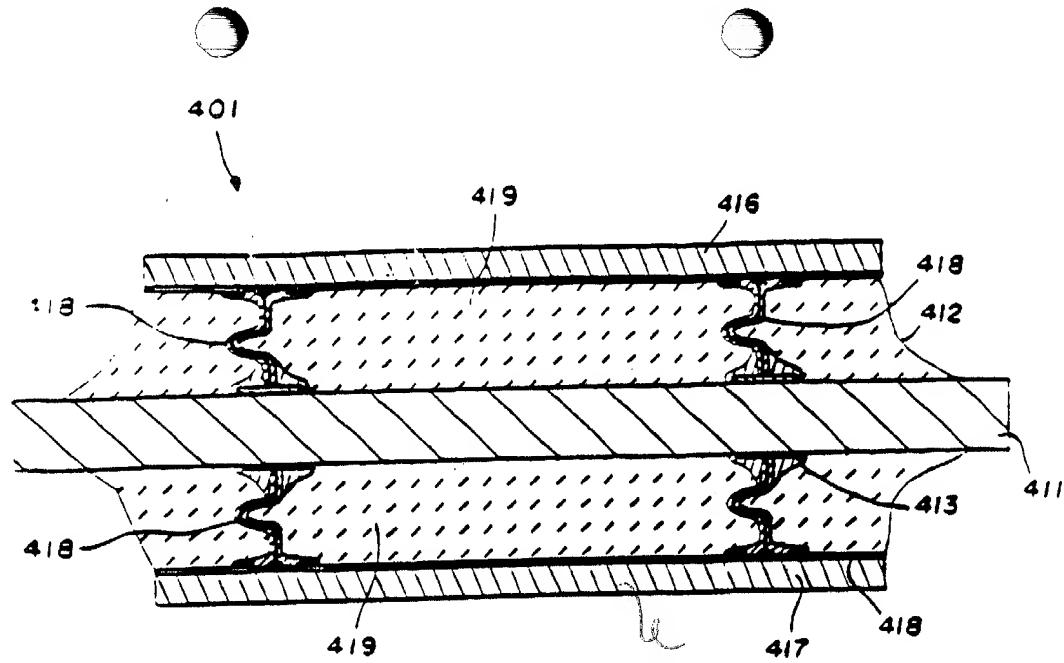


FIG. - 25

↑ delete all cross hatching

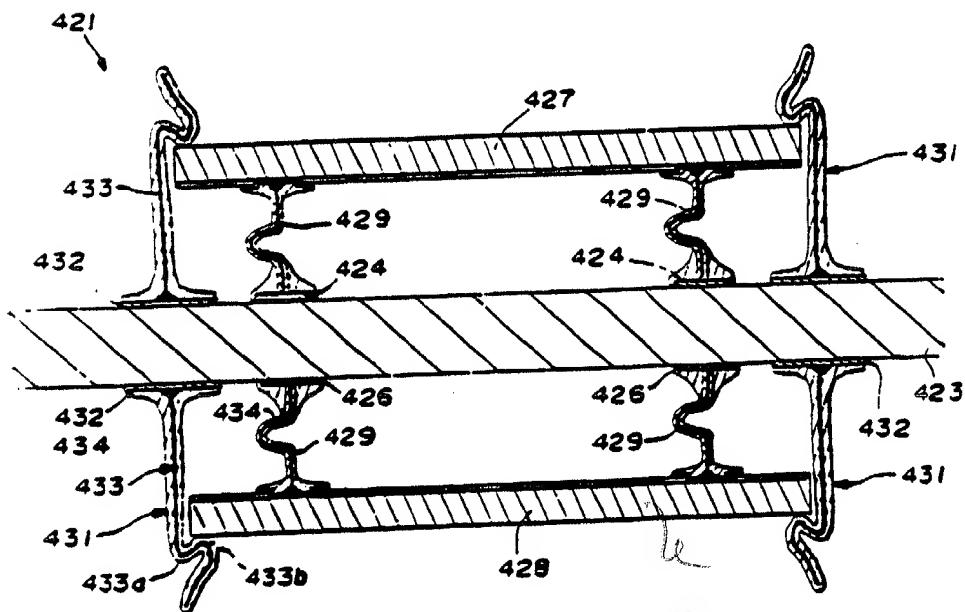


FIG. - 26

↑ delete all cross hatching

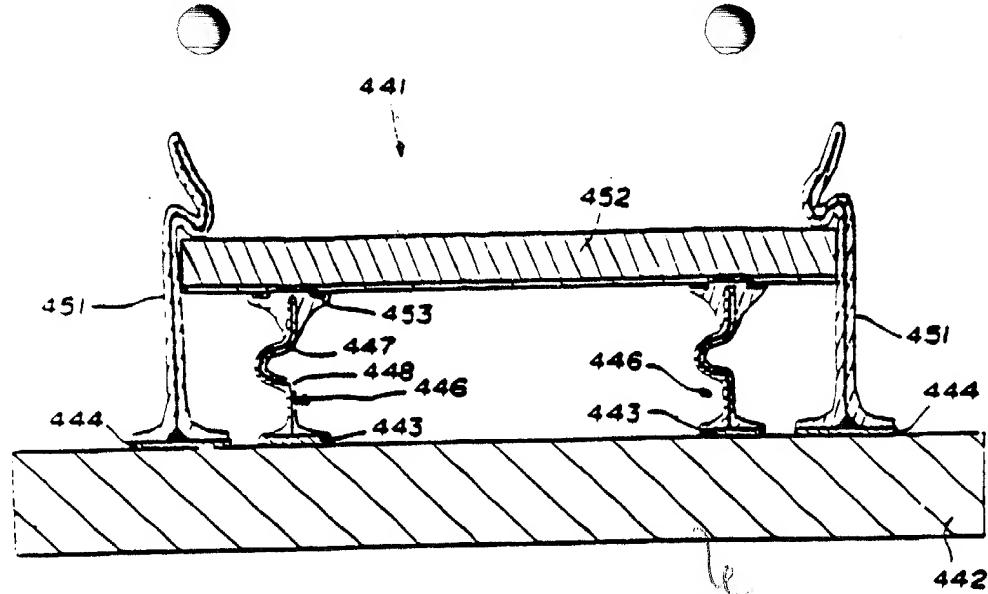


FIG. - 27

↑ delete all cross hatching

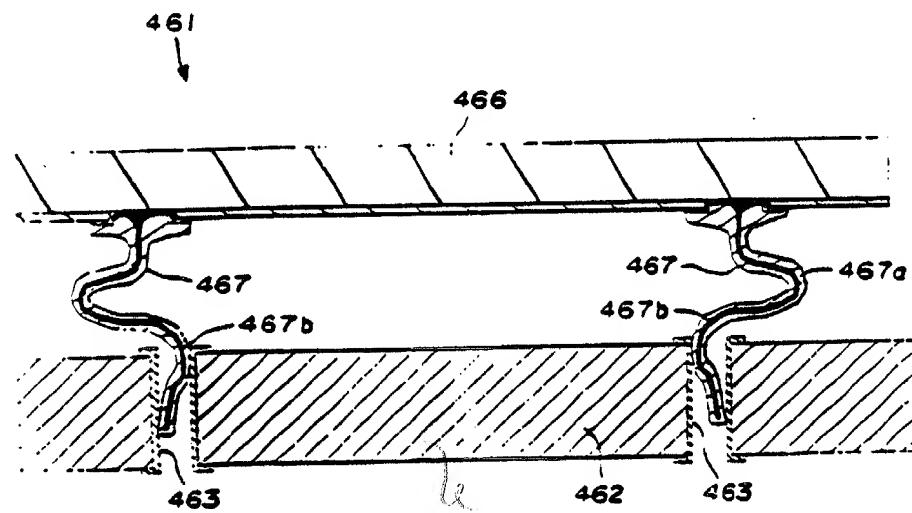


FIG. - 28

↑ delete all cross hatching

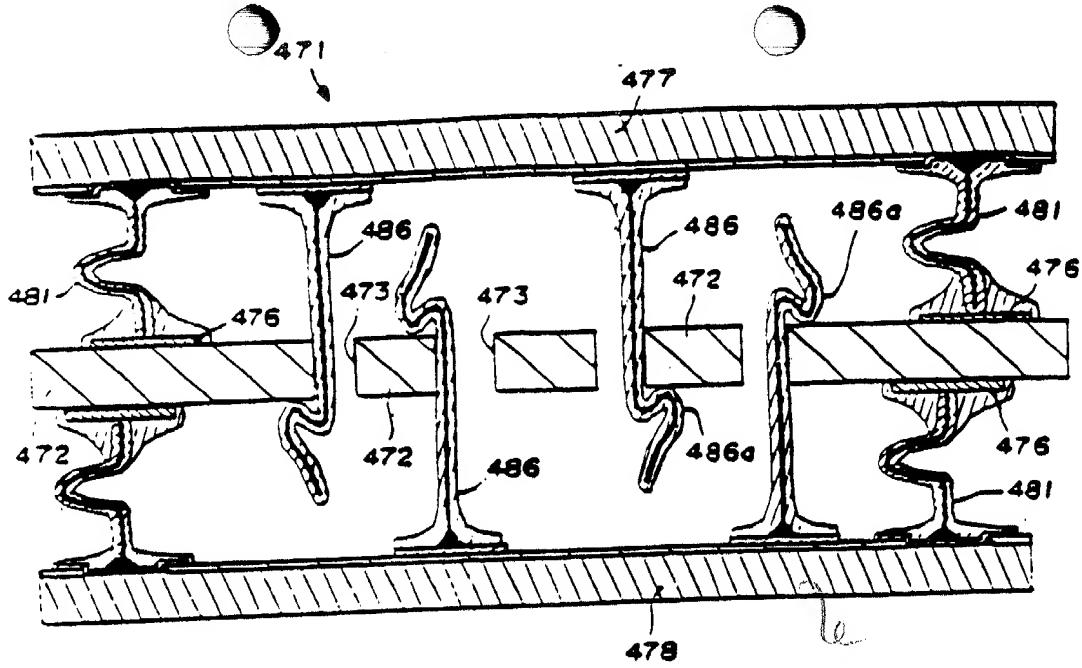


FIG. - 29

Delete all cross hatching

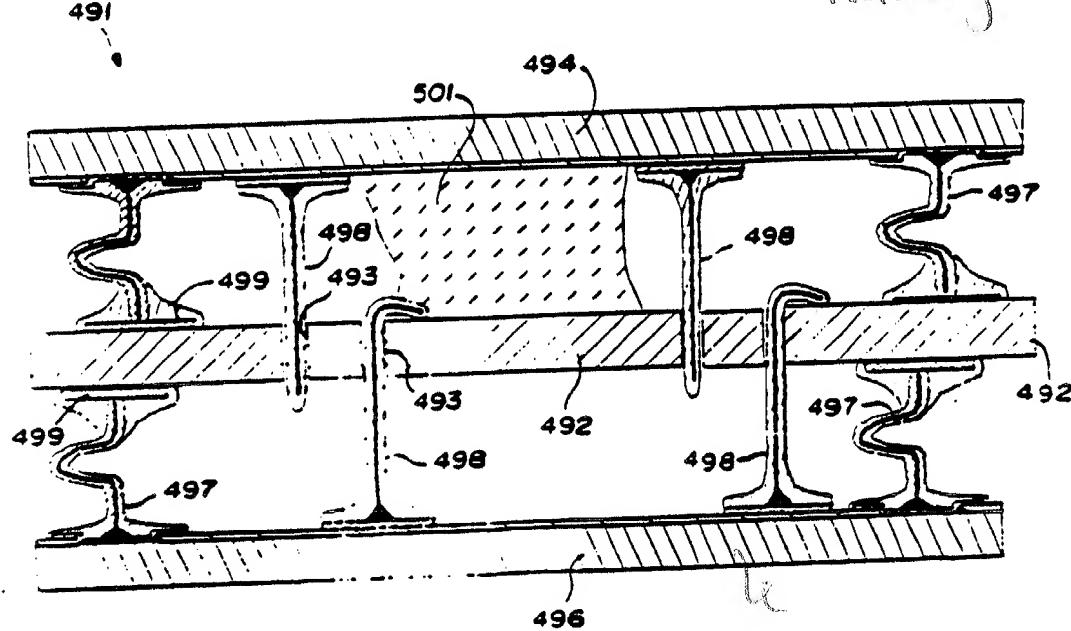


FIG. 30

Delete all cross hatching

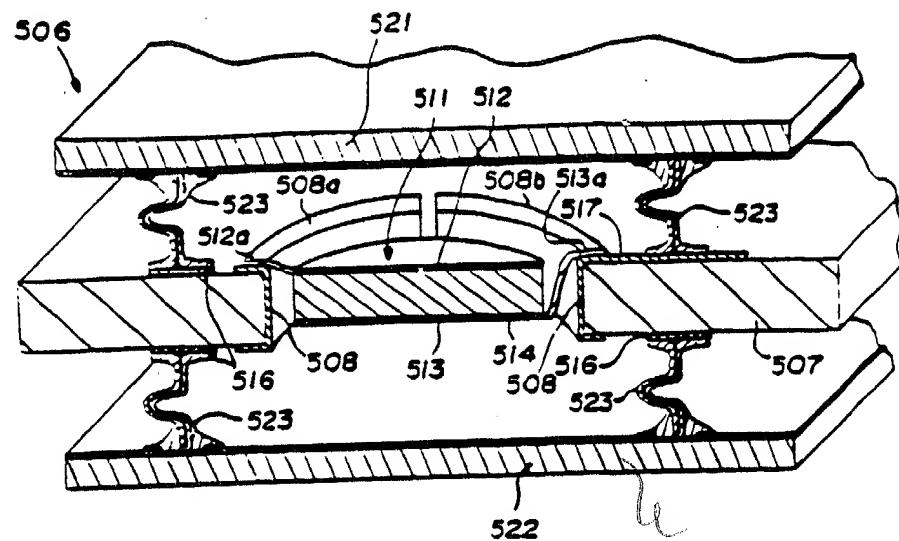


FIG. - 31

↑ delete all cross hatching

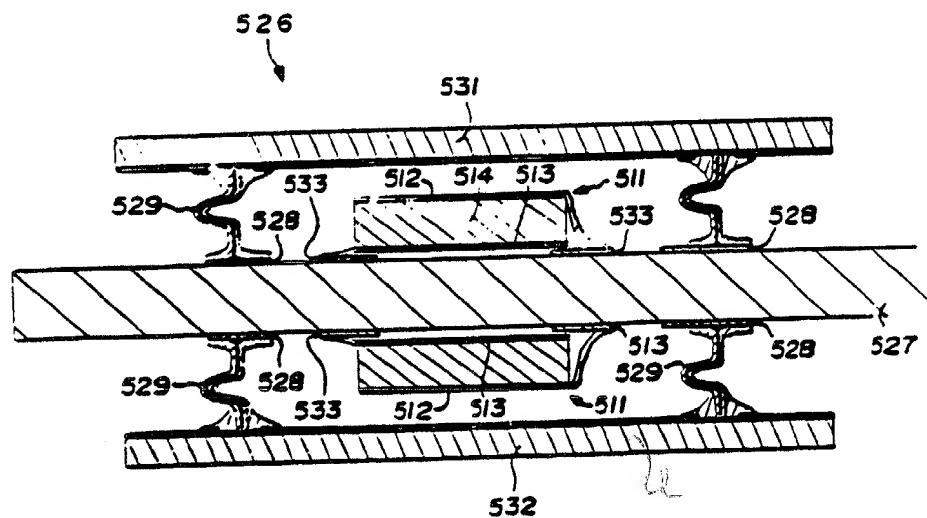


FIG. - 32

↑ delete all cross hatching

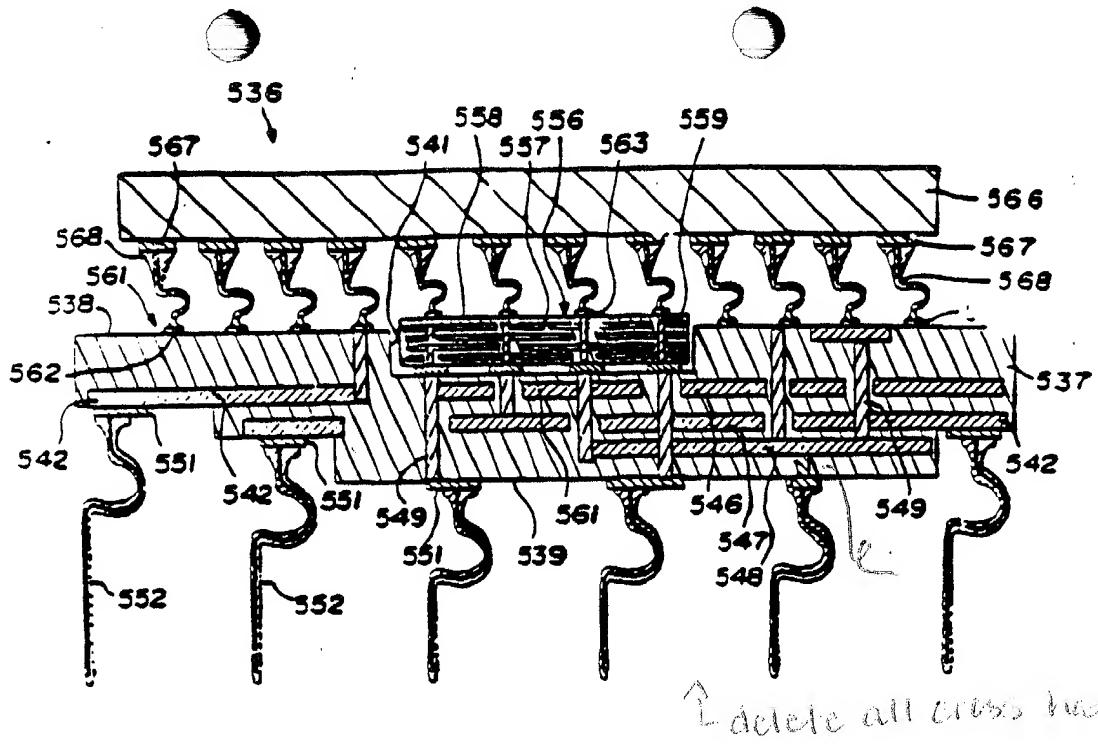


FIG. - 33

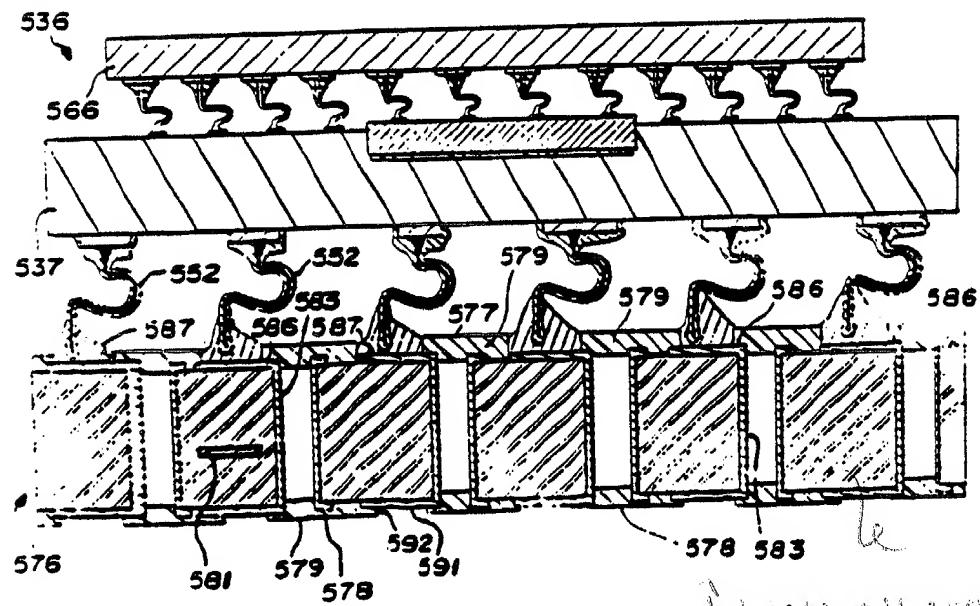


FIG. 34

I did all cross
hatching

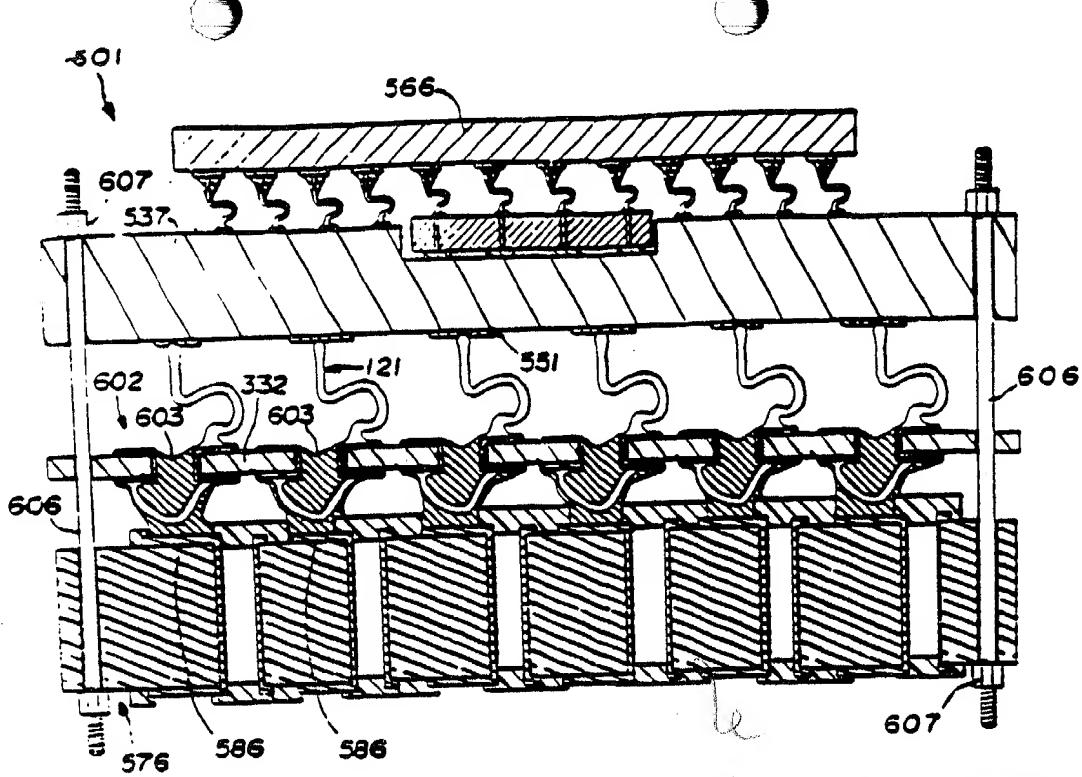


FIG. - 35

*Add all cross
hatching*

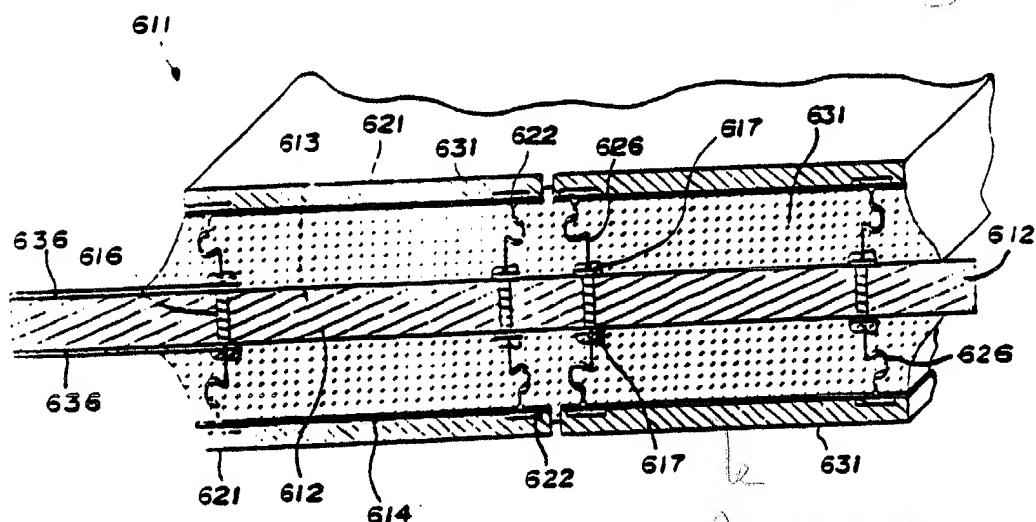


FIG. - 36

*Delete all cross
hatching*

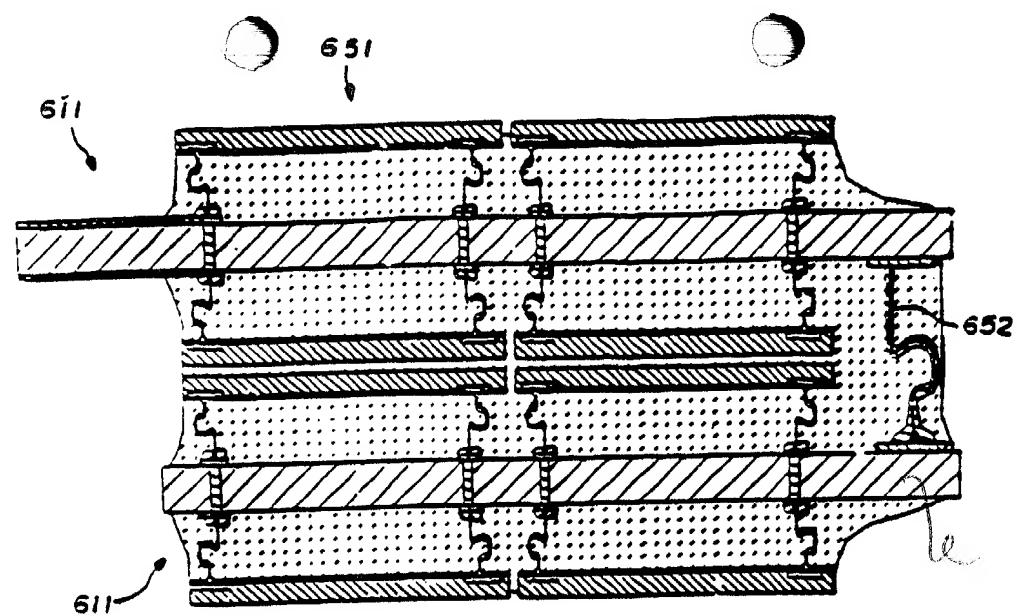


FIG.-37

↑ decide all cross
hatching

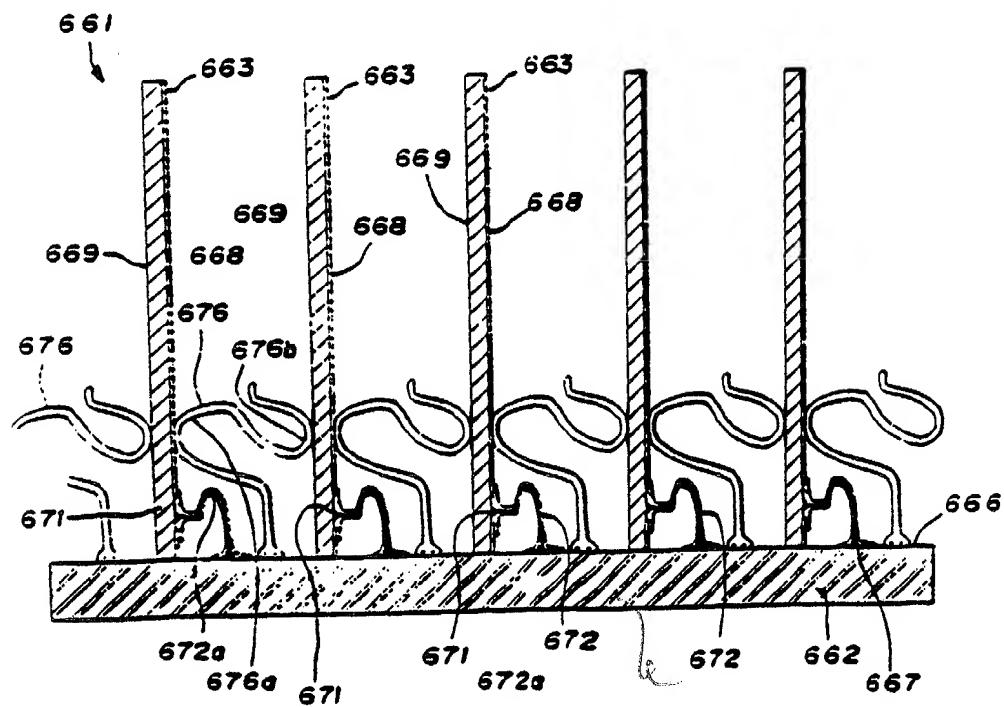


FIG. 38

1 delete all cross hatching